

AMENDMENTS TO THE CLAIMS

1. – 13. (Canceled)

14. (Currently Amended) A method for providing access to a circuit board, the method comprising the steps of:

applying force to a first surface of said circuit board to substantially balance a force causing mechanical distortion of said circuit board; and

contacting said first surface of said circuit board with a contact element having a surface area which is substantially smaller than an area of a region of interest on said first surface of said circuit board to impart said applied force to said first surface, thereby providing access to electrical contact points within a ~~vast majority portion of~~ said region of interest.

15. (Original) The method of claim 14 wherein the step of applying force comprises:

securing a frame in proximity to said circuit board; and

extending a compression link from said secured frame to said first surface of said circuit board to thereby apply force to said circuit board.

16. (Original) The method of claim 15 wherein the step of applying force comprises:

securing a frame in proximity to said circuit board;

generating force employing a compression mechanism attached to said secured frame;

and

transmitting said generated force to said first surface of said circuit board employing an extension link coupled to said compression mechanism.

17. (Original) The method of claim 14 further comprising the step of:

disposing a component of interest on a second surface of said circuit board located opposite said region of interest on said first surface of said circuit board; and

coupling said contact points within said region of interest with said component of interest.

18. (Original) The method of claim 17, further comprising the step of:
testing said component employing selected ones of said coupled contact points.
19. (Original) The method of claim 17, further comprising the step of:
supplying power to said component employing selected ones of said coupled contact
points.
20. (Original) The method of claim 17, wherein selected ones of said contact
points are upper edges of vias coupled to said component of interest.